

0083-0865-2



IN THE UNITED STATES PATENT & TRADEMARK OFFICE

#32
Anahita E
J. White
4-18-02
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APR 15 2002
TC 2800 MAIL ROOM

IN RE APPLICATION OF: :
Masashi GOTOH, et al. : EXAMINER: CUNEO, K.
SERIAL NO.: 09/119,626 :
RCE FILED: December 6, 2001 : GROUP ART UNIT: 2841
FOR: CIRCUIT BOARD HAVING :
BONDING AREAS TO BE
JOINED WITH BUMPS BY
ULTRASONIC BONDING

AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

In response to the Office Action dated January 14, 2002, please amend the above-identified application as follows:

IN THE CLAIMS

Claim 16 is amended as follows:

E) 16. (Once Amended) A chip part device comprising:
a circuit board including a board main body and a conductive layer formed on said board main body, said conductive layer having a plurality of bonding areas defined by a conductive pattern; and
a chip element mounted on said circuit board, and having a plurality of bump electrodes which are joined with said bonding areas by ultrasonic bonding,